

SURFACE MOUNT RECTIFIERS

**REVERSE VOLTAGE: 50 - 1000 V
CURRENT: 1.0 A**

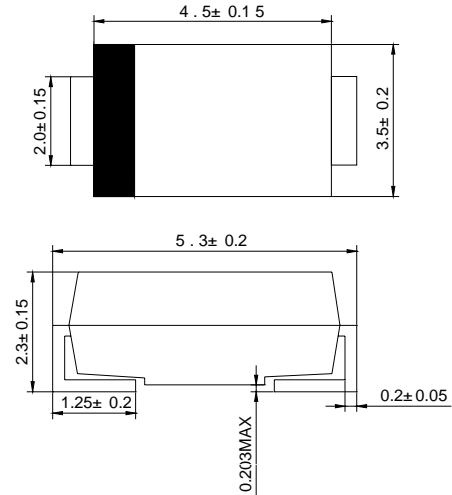
FEATURES

- ◇ Plastic package has underwriters laboratory flammability classifications
- ◇ For surface mounted applications
- ◇ Low profile package
- ◇ Built-in strain relief, ideal for automated placement
- ◇ High temperature soldering:
260°C/10 seconds at terminals

MECHANICAL DATA

- ◇ Case: JEDEC SMB, molded plastic over passivated chip
- ◇ Terminals: Solder Plated, solderable per ML-STD-750, Method 2026
- ◇ Polarity: Color band denotes cathode end
- ◇ Weight: 0.003 ounces, 0.093 grams

SMB



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

		S1AB	S1BB	S1DB	S1GB	S1JB	S1KB	S1MB	UNITS
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current @ $T_L=110^\circ\text{C}$	$I_{F(AV)}$	1.0							A
Peak forward surge current @ $T_L = 110^\circ\text{C}$ 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30							A
Maximum instantaneous forward voltage at 1.0A	V_F	1.1							V
Maximum DC reverse current @ $T_A=25^\circ\text{C}$ at rated DC blocking voltage @ $T_A=125^\circ\text{C}$	I_R	1.0 50							μA
Typical junction capacitance(NOTE 1)	C_J	12							pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	50							$^\circ\text{C/W}$
Operating junction and storage temperature range	$T_{JT_{STG}}$	-55-----+150							$^\circ\text{C}$

NOTE: 1. Measured at 1.0MHz and applied reverse voltage of 4.0volts

2. Thermal resistance from junction to ambient and junction to lead P.C.B mounted on 0.27"X0.27"(7.0X7.0mm2) copper pad areas.

FIG.1 – FORWARD DERATING CURVE

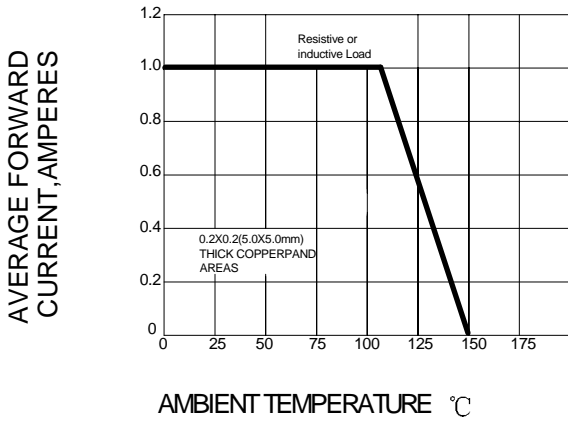


FIG.2 PEAK FORWARD SURGE CURRENT

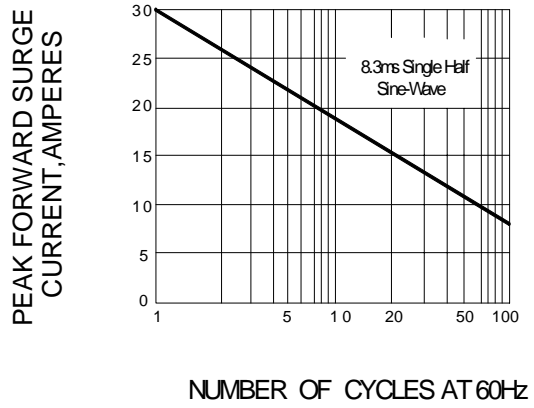


FIG.3 – TYPICAL FORWARD CHARACTERISTICS

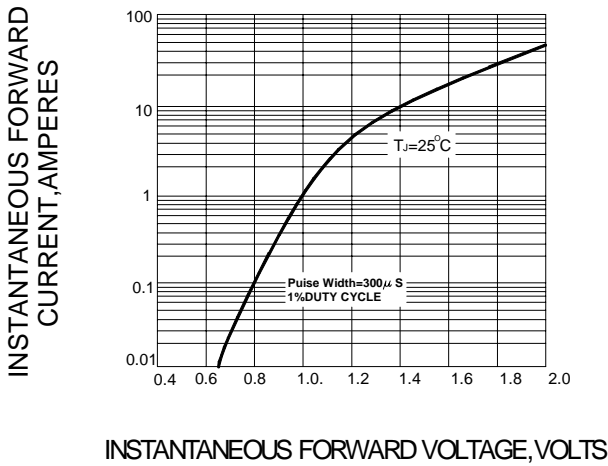


FIG.4 – TYPICAL REVERSE CHARACTERISTICS

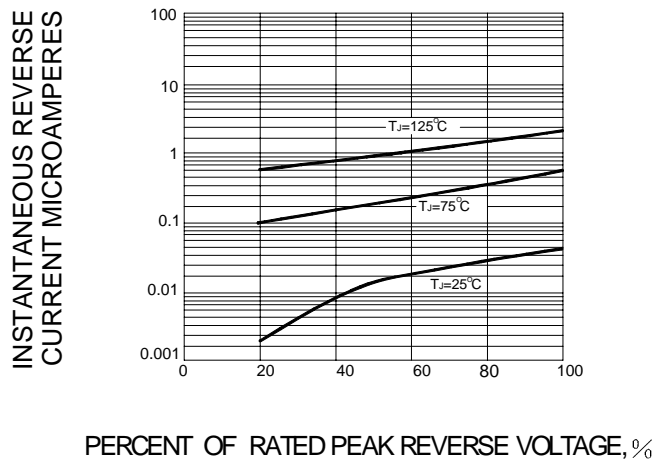


FIG.5-TYPICAL JUNCTION CAPACITANCE

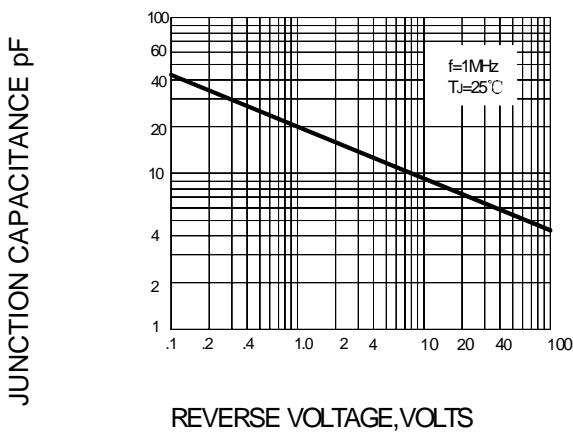


FIG.6-TRANSIENT THERMAL IMPEDANCE

